



## FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16981

Generic Copy

**Issue Date:** 08-Mar-2013

**TITLE:** WLP Process line transfer from Fujikura to internal site of LV5216CS-TE-L-E

**PROPOSED FIRST SHIP DATE:** 08-Jun-2013

**AFFECTED CHANGE CATEGORY(S):** WLP assembly location

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or <[Takashi.Asami@onsemi.com](mailto:Takashi.Asami@onsemi.com)>

**SAMPLES:** Contact your local ON Semiconductor Sales Office or <[Toshinobu.Tokita@onsemi.com](mailto:Toshinobu.Tokita@onsemi.com)>

**ADDITIONAL RELIABILITY DATA:** Available

Contact your local ON Semiconductor Sales Office or <[Satoru.Fujinuma@onsemi.com](mailto:Satoru.Fujinuma@onsemi.com)>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.

**DESCRIPTION AND PURPOSE:**

With the withdrawal Fujikura WLP, WLP processing plant will be transferred to the in-house (**Gunma CSP**) production plant from Fujikura.

The change point is not in package outline dimensions and structure.


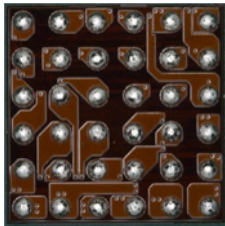

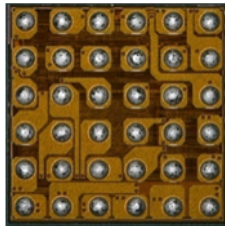
The change point of the appearance is color of the appearance by the difference of the resin and Cu RDL design.

Electrical specifications will remain identical.

Reliability Qualification and full electrical characterization over temperature has been completed.

**[Before the change]**

**[After the change]**

Before		After	
Mark area	Mold area	Mark area	Mold area
			



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### RELIABILITY DATA SUMMARY:

#### Reliability Test Results:

Test Items	Test Condition	Test Time	Failure
Steady State Operating Life	Tj=Tjmax,Vcc=Operating max	1000 h	0
Temperature Humidity Bias ※	Ta=85°C,RH=85%,Vcc=Recommended	1000 h	0
Temperature Humidity Storage ※	Ta=85°C,RH=85%	1000 h	0
Temperature Cycle ※	Ta=-55°C,30min.⇔Ta=150°C,30min.	100 Cycles	0
Pressure Cooker ※	Ta=121°C,RH=100% 2.03x10 <sup>5</sup> Pa	100 h	0
High Temperature Storage	Ta=150°C	1000 h	0
Low Temperature Storage	Ta=-55°C	1000 h	0
Resistance to Soldering heat (Reflow Soldering)	255°C, 10s(Peak 260°C)	2 times	0
Electrostatic Discharge(HBM)	Vcc pin versus each pin,Gnd pin versus each pin C=100pF,R=1500Ω,V=±1000V	3 times	0
Electrostatic Discharge(MM)	Vcc pin versus each pin,Gnd pin versus each pin C=200pF,R=0Ω,V=±150V	1 time	0

Notice) The test items with ※ mark are put into operation after the reflow soldering (at 255°C for 10seconds).

Judgment Criteria : Judgment Criteria are due to the limits of the electrical characteristics in the detail specification.

### ELECTRICAL CHARACTERISTIC SUMMARY:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

### CHANGED PART IDENTIFICATION:

The products after transfer have DTE (Manufacturing Date Code) #1319 and/or bigger (like #1320, #1321...) on the MPN Label.

### List of affected General Parts:

LV5216CS-TE-L-E